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(54) Title: CLIPPING MECHANISM FOR FASTENING A SUBSTRATE FOR A SURFACE TREATMENT OF THE SUBSTRATE

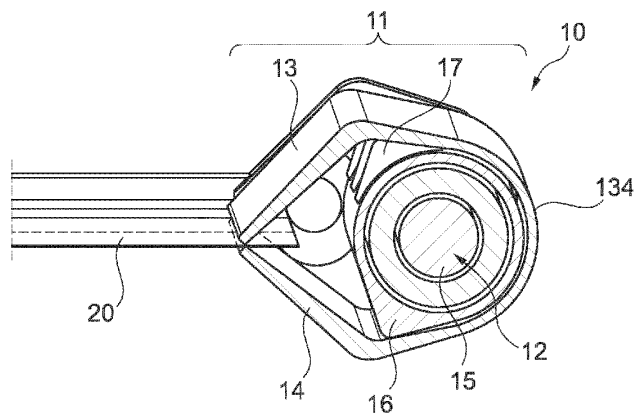


Fig. 1

(57) **Abstract:** The disclosure relates to a clipping mechanism for fastening a substrate for a surface treatment of the substrate, a clipping module for holding a substrate for a surface treatment of the substrate and a method for assembling a clipping mechanism for fastening a substrate for a surface treatment of the substrate. The clipping mechanism for fastening a substrate for a surface treatment of the substrate comprises a clipping bracket and an actuation unit. The clipping bracket comprises in a cross-section a first arm and a second arm. The first arm is moveable relative to the second arm to a receiving position for the substrate with a receiving distance between the first arm and the second arm. The first arm is moveable relative to the second arm to a fastening position for the substrate with a fastening distance between the first arm and the second arm. The fastening distance is smaller than the receiving distance. The actuation unit is at least partially surrounded by the clipping bracket. At least a portion of the actuation unit is moveable relative to the clipping bracket to move the first arm in the receiving position or the fastening position.

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